CLAIMS

1. A method of cutting a glass workpiece by using a laser beam, the method comprising:

cutting the glass workpiece by irradiating a first laser beam to the glass workpiece; and

processing a cut surface of the glass workpiece by irradiating a second laser beam to the cut surface of the glass workpiece,

wherein the first laser beam and the second laser beam have different wavelengths from each other, and

wherein the first laser beam has a wavelength of 1030 nm to 1080 nm and the second laser beam has a wavelength of 9.4 μm to 10.6 μm.

2. The method of claim 1, wherein the processing of the cut surface of the glass workpiece comprises irradiating the second laser beam to the cut surface of the glass workpiece for 2 seconds to 3 seconds.

3. The method of claim 1, wherein the cutting of the glass workpiece comprises irradiating the first laser beam along a curved line to make the cut surface of the glass workpiece curved.

4. The method of claim 1, wherein the first laser beam is a pulse laser beam having a pulse width of 100 ps to 1 fs.

5. An apparatus for cutting a glass workpiece by using a laser beam, the apparatus comprising:

a first light source configured to cut the glass workpiece by irradiating a first laser beam to the glass workpiece; and

a second light source configured to process a cut surface of the glass workpiece by irradiating a second laser beam to the cut surface of the glass workpiece,

wherein the first laser beam and the second laser beam have different wavelengths from each other, and

wherein the first laser beam has a wavelength of 1030 nm to 1080 nm and the second laser beam has a wavelength of 9.4 μm to 10.6 μm.

6. The apparatus of claim 5, wherein the second light source is a CO_2 laser light source.

7. The apparatus of claim 5, wherein the first laser beam is a pulse laser beam having a pulse width of 100 ps to 1 fs.